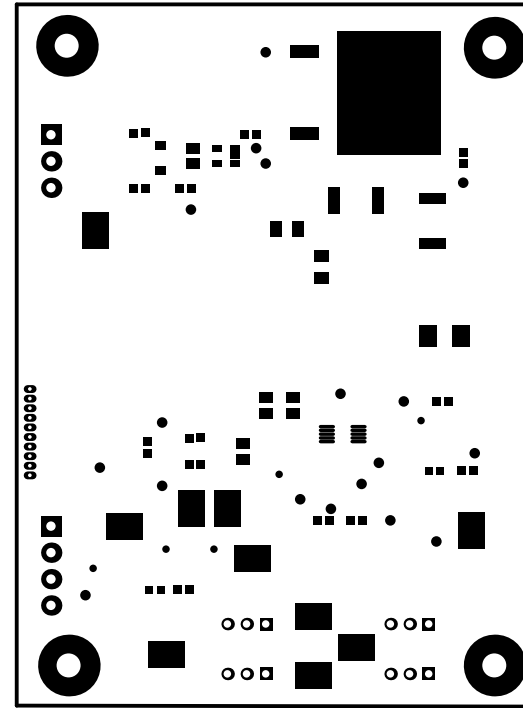
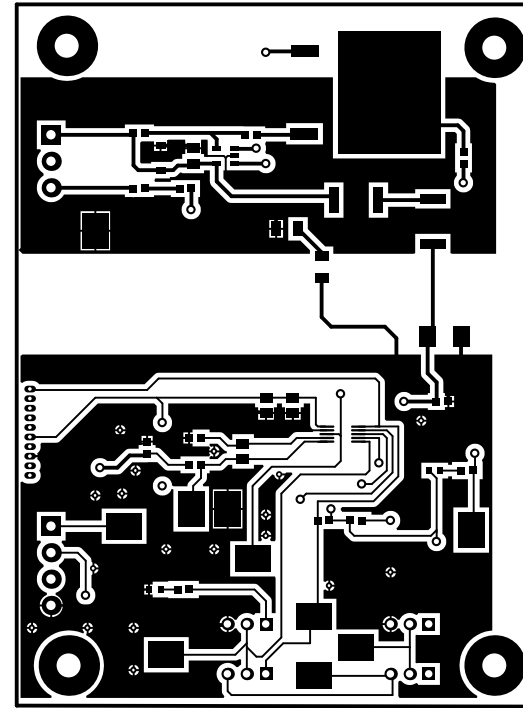


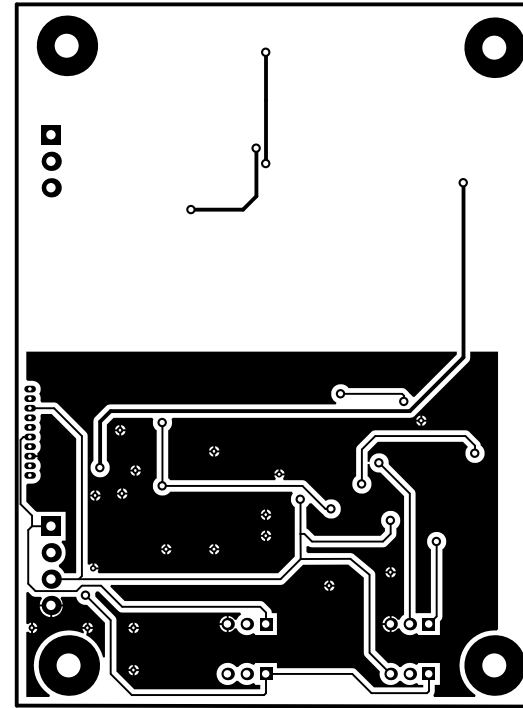
ALL artwork VIEWED FROM TOP SIDE	BOARD #: TIDA-00528	REV: 0	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Overlay	GENERATED : 11/23/2015 11:40:46 AM	TEXAS INSTRUMENTS	



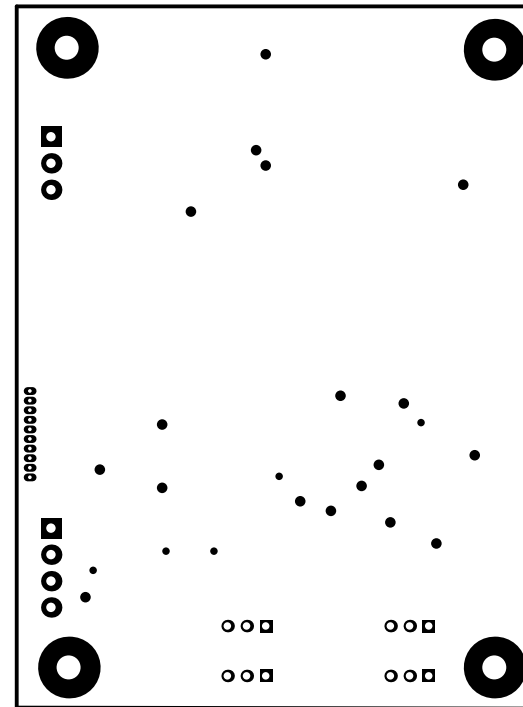
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00528	REV:	0	SUN REV:	Not In VersionControl
LAYER NAME =						
PLOT NAME =	Top Solder Mask	GENERATED :	11/23/2015	11:40:47 AM	TEXAS INSTRUMENTS	



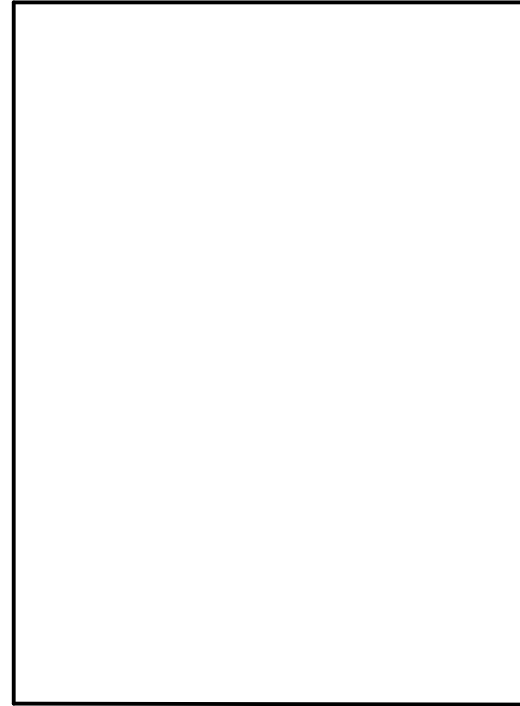
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00528	REV:	0	SUN REV:	Not In VersionControl
LAYER NAME =						
PLOT NAME =	Top Layer	GENERATED :	11/23/2015	11:40:47 AM	TEXAS INSTRUMENTS	



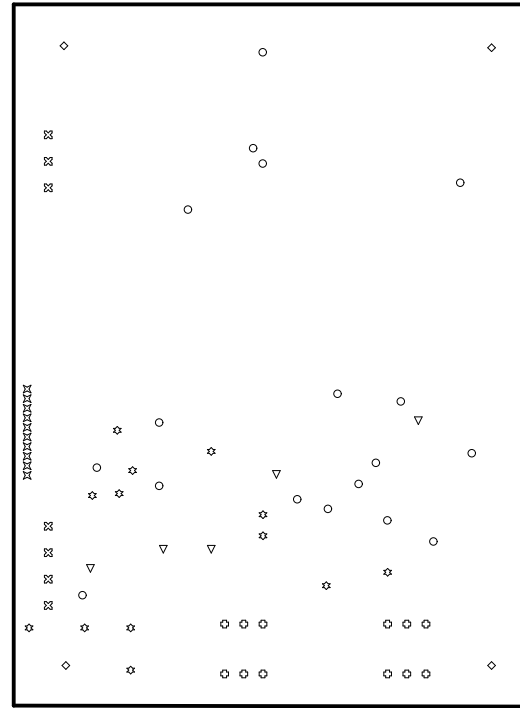
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00528	REV:	0	SUN REV:	Not In VersionControl
LAYER NAME =						
PLOT NAME =	Bottom Layer	GENERATED :	11/23/2015	11:40:48 AM	TEXAS INSTRUMENTS	



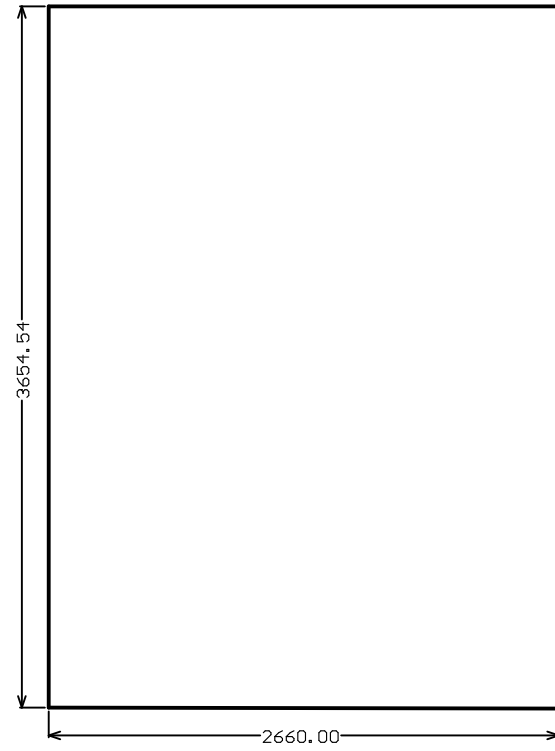
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00528	REV:	0	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Solder					
PLOT NAME =	Bottom Solder Mask		GENERATED :	11/23/2015	11:40:49 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00528	REV: 0	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Overlay	GENERATED : 11/23/2015 11:40:49 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00528	REV: 0	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/23/2015 11:40:50 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00528	REV: 0	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 11/23/2015 11:40:51 AM	TEXAS INSTRUMENTS	

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